

BORANG PERMOHONAN PENGGUNAAN PERALATAN  
**THERMAL CONSTANTS ANALYZER (Hot-Disk)**

Kategori Projek (*ProjectCategory*):  Tahun Akhir (*Final Year*)  MSc  PhD  
 Perundingan(*Consultation*)  R&D

Name of Applicant: .....

Email: ..... H/P: ..... USM ext. no.: .....

No. Matrix/IC: .....

School/Department: .....

Research Title: .....

Nama Sampel ( <i>Sample Name</i> )	Jenis Sampel ( <i>Sample Type</i> ) (Polymer, Composite, Metal and Ceramic)	Keadaan Sampel ( <i>Sample Condition</i> ) (Sheet, Thin Film, Liquid, and Powder)	Anggaran Kekonduksian Terma ( <i>Expectation Thermal Conductivity</i> ) (W/mK)	Suhu Ujian ( <i>Testing Temp.</i> ) (°C)	Suhu lebur ( <i>Melting point</i> ) (°C)	Ketebalan ( <i>Thickness</i> )	Bil. ( <i>Qty</i> )

**Note:**

- (1). Sensor sizes (D-diameter, mm): STANDARD (D=13), THIN FILM (D=30).
- (2). Sample thickness: STANDARD ( $\geq 3$  mm), THIN FILM (10 - 500  $\mu$ m)
- (3). Sample size must larger than sensor diameter. (Cylindrical shape is suggested)
- (4). Testing temperature range: Room temp. until 450 °C.
- (5). Only STANDARD allow to measure in high temp.
- (6). Please provide 2 pieces sample as 1 set sample except for liquid and powder.
- (7). *Thermal conductivity* and *Thermal diffusivity* can be obtained from this testing.

Tandatangan (*Applicant Signature*): \_\_\_\_\_ Tarikh (*Date*): \_\_\_\_\_

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**Kebenaran daripada Penyelia projek (*Supervisor Approval*)**

Saya \_\_\_\_\_, meluluskan permohonan untuk menggunakan kemudahan seperti di atas

Tarikh(*Date*): \_\_\_\_\_

\_\_\_\_\_  
( Tandatangan Penyelia Projek )  
*Supervisor Signature*

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**Kebenaran daripada Penyelia Peralatan (*Approval by Equipment In-Charge Supervisor*)**  
(*Prof. Ir. Dr. Mariatti Jaafar@Mustapha / \_\_\_\_\_*)

Tarikh(*Date*): \_\_\_\_\_

\_\_\_\_\_  
Tandatangan Penyelia Peralatan  
(*Approved by Equipment In-Charge Supervisor*)

